

Description

The HTH7G14S150H(B) is a unmatched discrete LDMOS Power Amplifier with 150W saturated output power covering frequency range from 1.8 - 1400 MHz.

Features

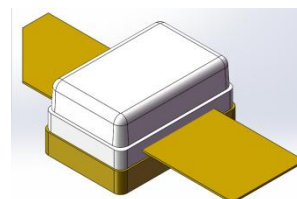
- Operating Frequency Range: 1.8 - 1400 MHz
- Operating Drain Voltage: 28-50V
- Saturation Output Power: 150W
- Internally Unmatched device
- Excellent thermal stability due to low thermal resistance package
- Enhanced robustness design without device degradation
- Internally integrated enhanced ESD design

Applications

- Industrial, scientific, medical (ISM)
 - Laser generation
 - Plasma generation
 - Particle accelerators
 - MRI, RF ablation and skin treatment
 - Industrial heating, welding and drying systems

Ordering Information

Part Number	Description
HTH7G14S150H(B)	Tray Package
HTH7G14S150H(B)EVB	860 MHz EVB

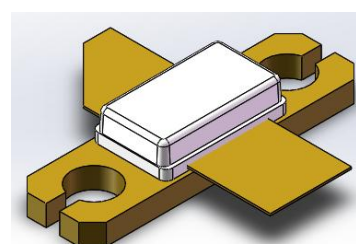


ACC0906S-2L

Earless Flanged balanced

Air Cavity Ceramic Package; 2 Leads

HTH7G14S150H



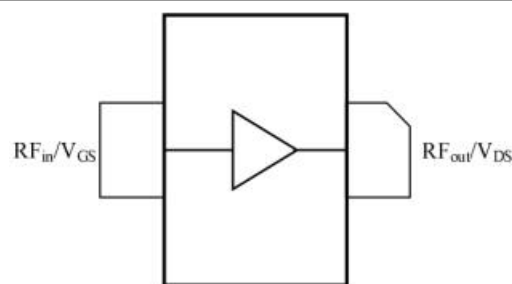
ACC0906B-2L

Flanged balanced

Air Cavity Ceramic Package; 2 Leads

2 Mounting Holes

HTH7G14S150HB



(Top View)

Note: Exposed backside of the package is the source terminal for the transistor

Pin Connections

Typical Performance

RF Characteristics (Pulsed CW)

Freq (MHz)	P1dB (dBm)	P1dB (W)	Gain (dB)	Eff(%)@P3dB
860	52.0	158	21.5	56.0

Test conditions unless otherwise noted: 25 °C, VDD = +50Vdc, IDQ = 300mA, PW = 100us, DC= 10% test on HOTLO Application Board

Absolute Maximum Ratings

Parameter	Range/Value	Unit
Drain voltage (V _{DSS})	-0.5 to +105	V
Gate voltage (V _{GS})	-5 to +10	V
Storage Temperature (T _{STG})	-55 to +150	°C
Junction Temperature (T _J)	-40 to +225	°C

Electrical Specification

DC Characteristics

Parameter	Conditions	Min	Typ	Max	Unit
Breakdown Voltage V _{(BR)DSS}	V _{gs} =0V, I _{ds} =100uA	105	-	-	V
Gate-Source Threshold Voltage V _{GS(th)}	V _{ds} =V _{gs} , I _{ds} =100uA	1.2	2.0	2.8	V
Drain Leakage Current I _{DSS}	V _{gs} =0V, V _{ds} =50V	-	-	10	uA
Gate Leakage Current I _{GSS}	V _{gs} =5V, V _{ds} =0V	-	-	1	uA

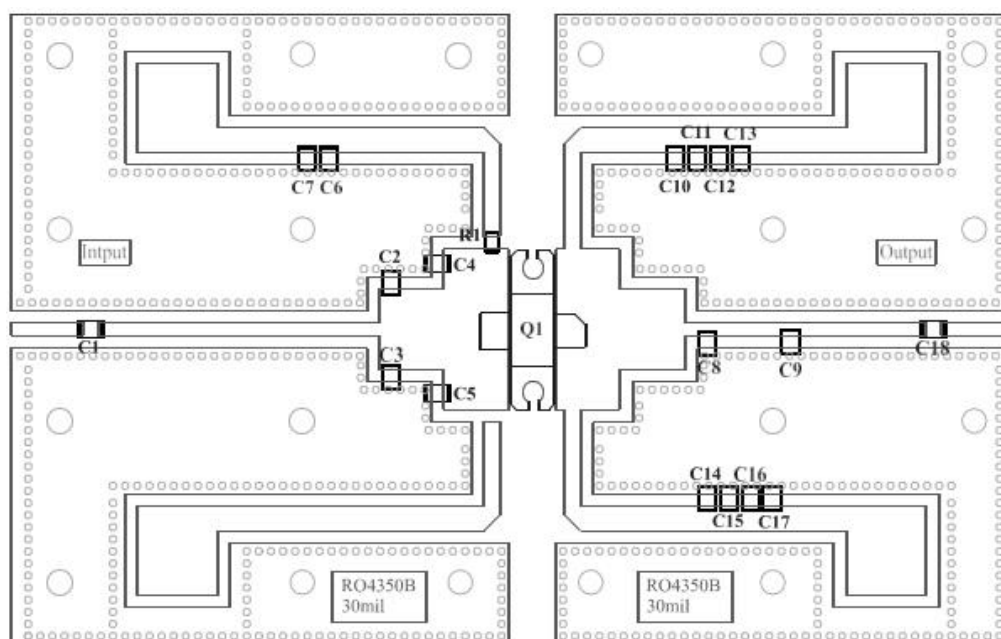
Load Mismatch Test

Condition	Test Result
VSWR=20:1 at all Phase Angles, VDD = +50Vdc, IDQ=300mA, Pout = 150W, PW = 200us, DC= 20%, freq@860 MHz	No Device Degradation

Thermal Information

Parameter	Condition	Value (Typ)	Unit
Thermal Resistance Junction to Case (R _{TH})	T _{FLANGE} = 60°C, VDD = +50Vdc, IDQ=300mA, Pout= 52 dBm (150W), PW = 100us, DC= 10%, freq@860 MHz	0.8	°C /W

HTH7G14S150H(B) 860 MHz Reference Design

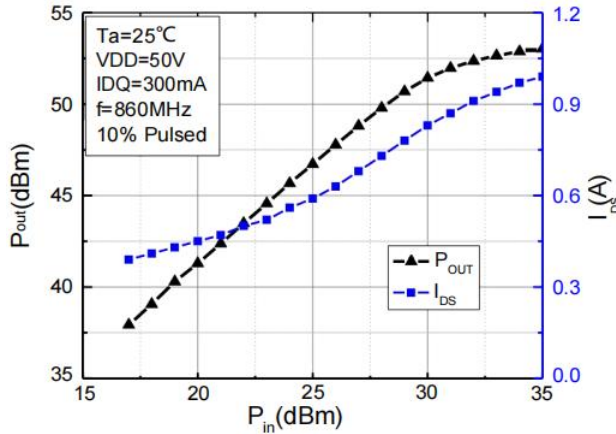


EVB Layout

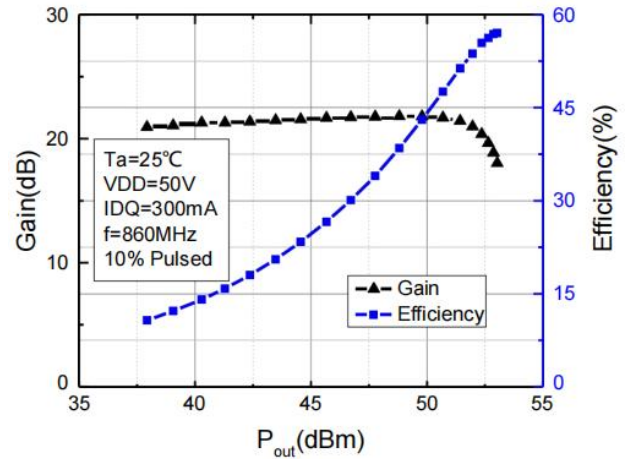
Bill of Materials (BoM) - HTH7G14S150H(B) 860 MHz Reference Design

Reference	Value	Description	Manufacturer	P/N
Q1	-	150W, 1.8 - 1400 MHz LDMOS PA	Holto	HTH7G14S150H(B)
C1, C6, C10, C14, C18	56pF	MLCC	ATC	ATC100B560JT500XT
C2	6.8pF	MLCC	ATC	ATC100B6R8JT500XT
C3	8.2pF	MLCC	ATC	ATC100B8R2JT500XT
C4, C5, C8	10pF	MLCC	ATC	ATC100B100JT500XT
C9	2.4pF	MLCC	ATC	ATC100B2R4JT500XT
C11, C15	10nF	MLCC	Murata	GR321AD72E103KW01D
C7, C12, C13, C16, C17	10uF	MLCC	Murata	GRM32EC72A106KE05
C19	10uF	MLCC	AVX	22201C106MAT2A
R1,	10Ω	Thick Film Resistor	YAGEO	RC0805FR-0710RL
PCB	Rogers4350B (er = 3.66), 30 mil (0.762 mm), 35 μm (1oz)			

Performance Plots

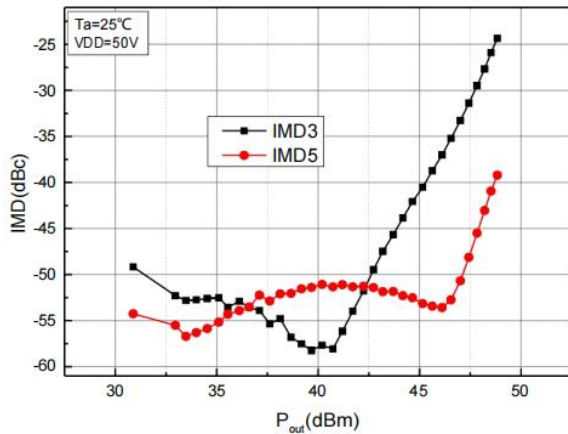


Pulsed CW, P_{out} vs P_{in}

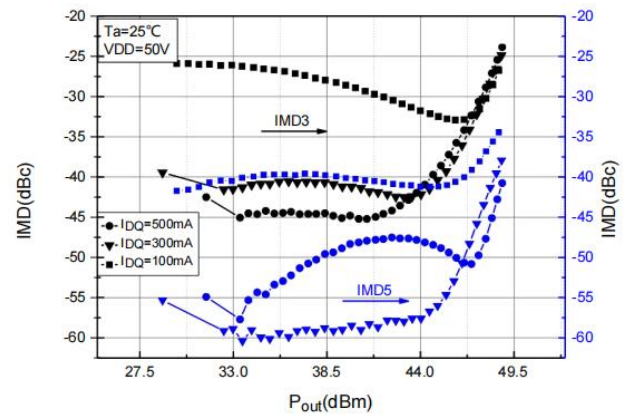


Pulsed CW, Gain and Efficiency vs P_{out}

Test conditions unless otherwise noted: 25°C , $V_{DD} = +50\text{dc}$, $IDQ = 300\text{mA}$, $PW = 100\mu\text{s}$, $DC = 10\%$ test on HOTLO Application Board



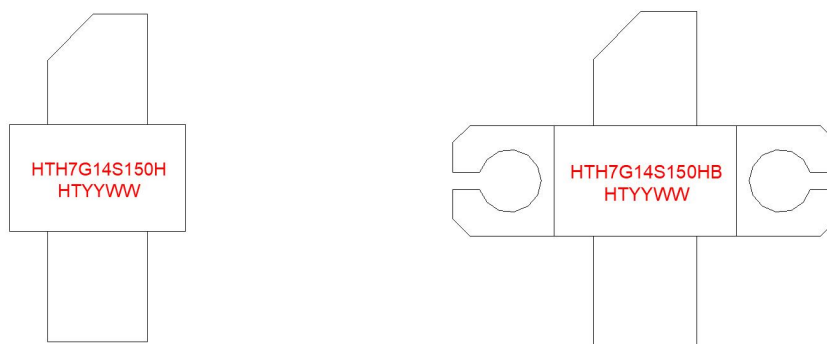
Two Tone IMD vs P_{out}



Two Tone IMD vs P_{out} @ IDQ 's

Test conditions unless otherwise noted: 25°C , $V_{DD} = +50\text{Vdc}$, $IDQ=300\text{mA}$, Two tone Test, Carrier Spacing @600KHz test on HOTLO Application Board

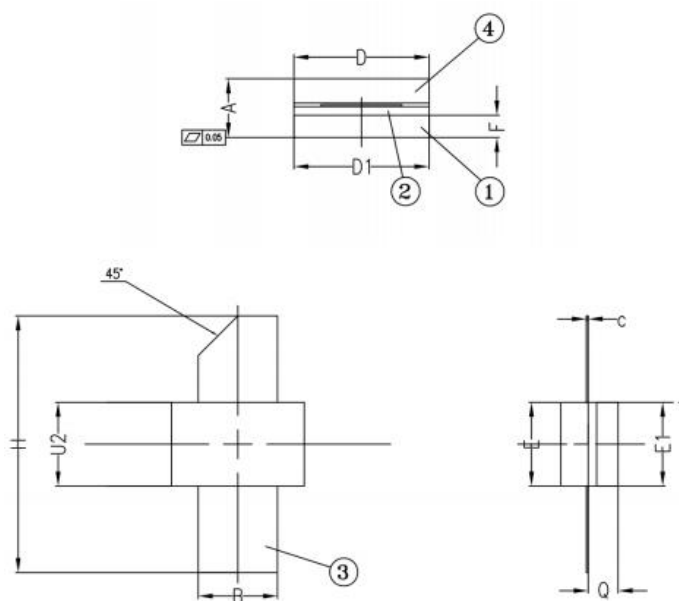
Package Marking and Dimensions



- Line1 (fixed): Device name in W/O
- Line2 (unfixed): HT+Date Code

This Marking SPEC only stipulates the content of Marking. For marking requirements such as font and size, please refer to the latest version of "Holto Product Printing Specification"

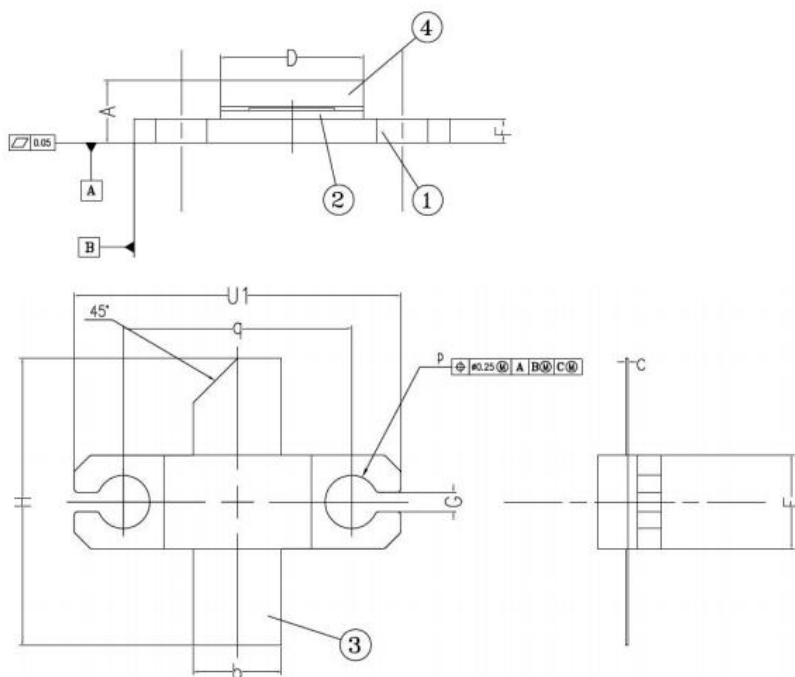
Marking



Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min.	Mon.	Max.	Min.	Mon.	Max.
A	3.84	3.98	4.12	0.151	0.157	0.162
B	5.37	5.50	5.63	5.211	0.217	0.222
C	0.11	0.13	0.15	0.004	0.005	0.006
D	9.07	9.20	9.33	0.357	0.362	0.367
D1	9.07	9.20	9.33	0.357	0.362	0.367
E	5.67	5.80	5.93	0.223	0.228	0.233
E1	5.67	5.80	5.93	0.223	0.228	0.233
F	1.37	1.50	1.63	0.054	0.059	0.064
H	17.30	17.80	18.30	0.681	0.701	0.720
Q	1.95	2.08	2.21	0.077	0.082	0.087
U2	5.67	5.80	5.93	0.223	0.228	0.233

Package Dimensions

ACC0906S-4L Earless Flanged Air Cavity Ceramic Package; 2 Leads



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Mon.	Max.	Min.	Mon.	Max.
A	3.84	3.98	4.12	0.151	0.157	0.162
b	5.37	5.50	5.63	5.211	0.217	0.222
c	0.11	0.13	0.15	0.004	0.005	0.006
D	9.07	9.20	9.33	0.357	0.362	0.367
E	5.67	5.80	5.93	0.223	0.228	0.233
F	1.37	1.50	1.63	0.054	0.059	0.064
G	1.07	1.20	1.33	0.042	0.047	0.052
H	17.30	17.80	18.30	0.681	0.701	0.720
p	3.05	3.3	3.55	0.120	0.130	0.140
q	14.07	14.20	14.33	0.554	0.559	0.564
U1	20.17	20.30	20.43	0.794	0.799	0.804

Package Dimensions

ACC0906B-2L Flanged balanced Air Cavity Ceramic Package; 2 Leads; 2 Mounting Holes

Tape and Reel Information


Package Type	Qty/Tray(pcs)	Qty/Box(pcs)
ACC0906	30	300



Packaging Descriptions

Handling Precautions

Parameter	Grade
Moisture Sensitivity Level MSL	3

Parameter	Rating	Standard	
ESD – Human Body Model (HBM)	Class 1B	JESD22-A114	
ESD – Human Body Model (MM)	Class A	EIA/JESD22-A115	
ESD – Charged Device Model (CDM)	Class III	JESD22-C101	

RoHS Compliance

This product is compliant with the 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment), as amended by Directive 2015/863/EU.

Datasheet Status

Document status	Product status	Definition
Objective Datasheet	Design simulation	Product objective specification
Preliminary Datasheet	Customer sample	Engineering samples and first test results
Product Datasheet	Mass production	Final product specification

Abbreviations

Acronym	Definition
LDMOS	Laterally-Diffused Metal-Oxide Semiconductor
CW	Continuous Waveform

Revision history

Document ID	Datasheet Status	Release Date	Revision Version
Rev 2.2	Product	March 2023	New format based on English version datasheet
Rev 2.3	Product	Sept. 2023	Update TBD information
Rev 2.4	Product	March 2024	Version released after re review

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations and information about HOTLO:

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